

FORM PTO-1449
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U.S. PATENT DOCUMENTS

| Exmr Initial | Document Number | Date | Name | Class | Sub Class | Filing Date |
|-----------------|--------------------|----------|------------------|-------|--------------|----------------|
| JHA | 4,925,525 | 05/15/90 | Oku et al. | | | |
| JHA | 4,980,217 | 12/25/90 | Grundfest et al. | | | |
| JHA | 5,004,639 | 04/02/91 | Desai | | | |
| JHA | 5,050,038 | 09/17/91 | Malaurie et al. | | | |
| JHA | 5,114,518 | 05/19/92 | Hofarth et al. | | | |
| JHA | 5,252,195 | 10/12/93 | Kobayashi et al. | | | |
| JHA | 5,277,787 | 01/11/94 | Otani et al. | | | |
| JHA | 5,288,542 | 02/22/94 | Cibulsky et al. | | | |
| JHA | 5,418,689 | 05/23/95 | Alpaugh et al. | | | |
| JHA | 5,468,999 | 11/21/95 | Lin et al. | | | |
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| JHA | 5,500,555 | 03/19/96 | Ley | | | |
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OTHER DOCUMENTS

(Including Author, Title, Date, Pertinent Pages, Etc.)

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| JHA | 1) | "Chapter 12: Printed Circuit Board Packaging," <i>Microelectronics Packaging Handbook</i> , Tummala, Rao R., et al., Editors, and Klopfenstein, Alan G., Managing Editor, Van Nostrand Reinhold (New York) 1989, pp. 863-921. |
| JHA | 2) | "Electrochemical Migration in Multichip Modules," Rudra, B., et al., <i>Circuit World</i> , Vol. 22, No. 1, 1995, pp. 67-70. |
| JHA | 3) | "Microstructure of Conductive Anodic Filaments Formed during Accelerated Testing of Printed Wiring Boards," Ready, W. J., et al., <i>Circuit World</i> , Vol. 21, No. 4, 1995, pp. 5-9. |

Examiner

Jose H. Alcala

Date Considered

12/10/02

Examiner: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.